TEXAS INSTRUMENTS 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

The purpose of this version A is to retract devices that were inadvertently included and is not affected by this change. We apologize for any inconvenience this may have caused.

PCN Number:	20260223007.1A	**PCN Date:**	November 12, 2026
Title:	Add Cu as Alternative Wire Base Metal for Selected Device(s)		
Customer Contact:	Change Management team	**Dept:**	Quality Services

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Revision A is to remove devices in the Product Affected Section (with ~~strikethrough~~) and highlighted in yellow. These devices were inadvertently added and are not affected by this change.

Texas Instruments is pleased to announce the qualification of new assembly material set to add Cu as an additional bond wire option for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows:

Group 1

Material	Current	Proposed
Wire diam/type	0.96mil Au + 0.8mil Cu	0.8mil Cu

Group 2

Material	Current	Proposed
Wire diam/type	0.8mil Au, 0.96mil Au	0.8mil Cu

Group 3

Material	Current	Proposed
Wire diam/type	0.90mil Au, 0.96mil Au, 1.18mil Au	0.96mil Cu

Reason for Change:

Continuity of supply.

1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties
2) Maximize flexibility within our Assembly/Test production sites.
3) Cu is easier to obtain and stock

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

Review the SDP for full evaluation of the change based on the customer use case.

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

None

Group 1 Product Affected:

ISOW1044BDFMR	ISOW7721FDFMR	ISOW7742DFMR
ISOW1044DFMR	ISOW7740DFMR	ISOW7742FDFMR
ISOW1412BDFMR	ISOW7740FDFMR	ISOW7743DFMR
ISOW1412DFMR	ISOW7741BDFMR	ISOW7743FDFMR
ISOW1432BDFMR	ISOW7741DFMR	ISOW7744DFMR
ISOW1432DFMR	ISOW7741FBDFMR	ISOW7744FDFMR
ISOW7721DFMR	ISOW7741FDFMR	

Group 2 Product Affected:

ADS5281IRGCR	CDCE937PWR	CDCS502PWR
ADS5281IRGCT	CDCE937PWRG4	CDCS503PW
ADS5282IRGCR	CDCE937R01PWR	CDCS503PWR
ADS5282IRGCT	CDCE937R02PWR	SN1002030RGZR
CDC734PWR	CDCE937R04PWR	SN1301027IRGCT
~~CDCE913PW~~	CDCE937R07PWR	SN74ABT646ANSR
~~CDCE913PWG4~~	~~CDCE949PW~~	SN74ALVC245NSR
~~CDCE913PWR~~	~~CDCE949PWG4~~	SN74CBTLV3861NSR
~~CDCE913PWRG4~~	~~CDCE949PWR~~	SN74LVC2244ANSR
CDCE913R01PWR	CDCE949R03PWR	SN74LVC245ANS
CDCE913R02PWR	CDCE949R04PWR	SN74LVC245ANSR
CDCE913R05PWR	CDCE949R05PWR	SN74LVC541ANS
CDCE913R07PWR	CDCEL824PWR	SN74LVCC3245ANSR
CDCE913R08PWR	CDCEL913PW	SN74LVCC4245ANS
CDCE913R09PWR	CDCEL913PWR	SN74LVCC4245ANSR
CDCE913R0APWR	CDCEL925PW	SN74LVCH245ANSR
CDCE913R0BPWR	CDCEL925PWR	SNB6006PW-P
CDCE913R0CPWR	CDCEL937PW	SNB6006PWR-P
CDCE925PW	CDCEL937PWR	TLV320AIC3110IRHBT
CDCE925PWG4	CDCEL937R08PWR	~~TLV320DAC3100IRHBR~~
CDCE925PWR	CDCEL937R09PWR	~~TLV320DAC3100IRHBT~~
CDCE925R01PWR	CDCEL949PW	TLV320DAC3101IRHBT
CDCE925R02PWR	CDCEL949PWR	TLV320DAC3120IRHBT
CDCE925R04PWR	~~CDCS501PW~~	TUSB3410IRHBT
CDCE937PW	~~CDCS501PWR~~	TUSB3410RHBT
CDCE937PWG4	CDCS502PW	

Group 3 Product Affected:

74AVC16T245DGGR-P	INA828ID	OPA4172IDR
74LVCH16245ADGGRG4	INA828IDR	OPA4180ID
ADS1119IPW	INA848ID	OPA4180IDR
ADS1119IPWR	INA848IDR	OPA4191ID
ADS1119IPWT	LM380N/NOPB	OPA4191IDR
ADS112C04IPW	LM384N/NOPB	OPA4191IPWR
ADS112C04IPWR	MSP430V303IRHAR	OPA4191IPWT
ADS112U04IPW	MSP430V331IRHAR	OPA4192ID
ADS112U04IPWR	MSP430V424IRHAR	OPA4192IDR
ADS1219IPW	MUX36D04IPW	OPA4196ID
ADS1219IPWR	MUX36D04IPWR	OPA4196IDR
ADS1219IPWT	MUX36S08IPW	OPA4197ID
ADS122C04IPW	MUX36S08IPWR	OPA4197IDR
ADS122C04IPWR	MUX508IPW	OPA4316IPW
ADS122U04IPW	MUX508IPWR	OPA4316IPWR
ADS122U04IPWR	MUX508IWPWR	OPA4317ID
ADS1262IPW	MUX509IPW	OPA4317IDR
ADS1262IPWR	MUX509IPWR	OPA828ID
ADS7253IPW	MUX509IWPWR	OPA828IDR
ADS7253IPWR	OPA140AID	PSN07069A0PWR
ADS7254IPW	OPA141AID	~~REF5010AIDR~~
ADS7254IPWR	OPA141AIDR	~~REF5020AID~~
ADS7853IPW	OPA145ID	~~REF5020AIDR~~
ADS7853IPWR	OPA145IDR	REF5045AIDR
ADS7854IPW	OPA1612AID	SN07069PWR
ADS7854IPWR	OPA1612AIDR	SN1272DR
ADS8353IPW	OPA1654AIPW	SN74ALVCF162834DL
ADS8353IPWR	OPA1654AIPWR	SN74AVCH20T245GR
ADS8354IPW	OPA1679IPWR	SN74LVC541ADB
ADS8354IPWR	OPA1688ID	SN74LVC541ADBR
ADS8661IPW	OPA1688IDR	SN74LVC541ANSR
ADS8661IPWR	OPA170AID	SN74LVCH16245ADGG
ADS8665IPW	OPA171AID	SN74LVCH16245AG-P
ADS8665IPWR	OPA171AIDR	SN74LVCH245ADBR
ADS8671IPW	OPA172ID	SN74LVTH373NSR
ADS8671IPWR	OPA172IDR	SN74LVTH574NSR
ADS8675IPW	OPA180ID	THS4531AID
ADS8675IPWR	OPA180IDR	THS4531AIDR
ADS8681IPW	OPA188AID	TLV170IDR
ADS8681IPWR	OPA188AIDR	TLV171IDR
ADS8685IPW	OPA191ID	TLV172IDR
ADS8685IPWR	OPA191IDR	TLV2170IDR
ADS8689IPW	OPA192ID	~~TLV2171IDGKR~~
ADS8689IPWR	OPA192IDR	~~TLV2171IDGKT~~
ADS8691IPW	OPA196ID	TLV2171IDR

ADS8691IPWR	OPA196IDR	TLV2172IDR
ADS8695IPW	OPA197ID	TLV2316IDR
ADS8695IPWR	OPA197IDR	TLV2376IDR
ADS8699IPW	OPA202ID	TLV2379IDR
ADS8699IPWR	OPA202IDR	TLV333IDR
AVC16T245DGGR-D	OPA209AID	TLV3502AID
CC1070RGWR	OPA2172ID	TLV3502AIDG4
CC1070RGWT	OPA2172IDR	TLV3502AIDR
DAC60004IPW	OPA2187ID	TLV376IDR
DAC60004IPWR	OPA2187IDR	TLV4170ID
DAC70004IPW	OPA2191ID	TLV4170IDR
DAC70004IPWR	OPA2191IDR	TLV4171ID
DAC80004IPW	OPA2192ID	TLV4171IDR
DAC80004IPWR	OPA2192IDR	TLV4172IDR
DRV110APWR	OPA2196ID	TLV4313IPWR
INA1650IPW	OPA2197ID	TLV4316IPWR
INA1650IPWR	OPA2197IDR	TLV4333IDR
INA1651IPW	OPA2210ID	TLV4379IPWR
INA1651IPWR	OPA2210IDR	TMUX8108PWR
INA188ID	OPA2316ID	TPS659101A1RSLR
INA188IDR	OPA2316IDR	TPS6591023A1RSLR
INA818ID	OPA2320AID	TPS6591023A1RSLT
INA818IDR	OPA2320AIDR	TPS65910A1RSLR-P
INA819ID	OPA2322AID	TPS65910A3A1RSL
INA819IDR	OPA4140AID	TPS65910A3A1RSLR
INA821ID	OPA4140AIDR	TPS65910AA1RSLR
INA821IDR	OPA4172ID	

Group 1 Qualification Report

Automotive New Product Qualification Summary

(As per AEC-Q100 Rev. J and JEDEC Guidelines)
Approve Date 07-May-2025

Product Attributes

Attributes	Qual Device: ISOW7741QDFMRQ1	QBS Process Reference: ISO7741FQDWQ1	QBS Package Reference: AMC1305M25QDWQ1	QBS Package Reference: AMC131M03QDFMRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Power Management	Interface	Signal Chain	Signal Chain
Wafer Fab Supplier	FR-BIP-1, DMOS6, MH8, MH8	MH8, MH8	DP1DM5, DP1DM5, AIZU	DMOS6, MH8, MH8
Assembly Site	TAI	TAI	TAI	TAI
Package Group	SOIC	SOIC	SOIC	SOIC
Package Designator	DFM	DW	DW	DFM
Pin Count	20	16	16	20

QBS: Qual By Similarity, also known as Generic Data
Qual Device ISOW1044DFMR is qualified at MSL3 260C
Qual Device ISOW7741QDFMRQ1 is qualified at MSL3 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: ISOW7741QDFMRQ1	QBS Process Reference: ISO7741FQDWQ1	QBS Package Reference: AMC1305M25QDWQ1	QBS Package Reference: AMC131M03QDFMRQ1
Test Group A - Accelerated Environment Stress Tests											
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	-	Pass	-	Pass	Pass
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	110C/85%RH	264 Hours	-	-	-	3/231/0
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	110C/85%RH	264 Hours	-	-	-	3/231/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	-	3/231/0	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	1/5/0	-	1/5/0	1/5/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	-	-	-	3/135/0
Test Group B - Accelerated Lifetime Simulation Tests											
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	3/231/0	-	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-

Test Group C - Package Assembly Integrity Tests											
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/90/0	3/90/0	-
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/90/0	3/90/0	-
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	-	-	1/15/0
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	-	1/15/0
Test Group D - Die Fabrication Reliability Tests											
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests											
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	-	1/3/0	-	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	-	1/3/0	-	-
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	-	1/6/0	-	-
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	1/30/0	3/90/0	-	-

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Ambient Operating Temperature by Automotive Grade Level:
Grade 0 (or E): -40C to +150C
Grade 1 (or Q): -40C to +125C
Grade 2 (or T): -40C to +105C
Grade 3 (or I) : -40C to +85C
E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):
Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
Room : AC/uHAST
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2312-048

Group 2 & 3
Qualification Report
Approve Date 15-FEBRUARY -2026

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	QBS Package Reference: MC33063ADR	QBS Package Reference: XMSM0L1306SDGS28R	QBS Package Reference: TMUX1134PWR	QBS Package Reference: TPS51916RUKR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	3/231/0	-	-	3/231/0
HTOL	B1	Life Test	125C	1000 Hours	2/154/0	-	3/231/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	1/22/0	1/22/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0

QBS: Qual By Similarity, also known as Generic Data
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2602-072

Qualification Report
Approve Date 15-FEBRUARY -2026

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	QBS Package Reference: INA849DR	QBS Package Reference: SRC4190IDB	QBS Package Reference: TLC6946DBQR	QBS Package Reference: LM2594HVN-ADJ/NOPB	QBS Package Reference: TPD3S714QDBQRQ1	QBS Package Reference: TMUX1134PWR	QBS Package Reference: TRF7970AIRHBR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0	-	3/231/0	3/231/0
HAST	A2	Temperature Humidity Bias	85C/85%RH	1000 Hours	3/231/0	-	-	-	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	3/231/0	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	-	3/231/0	-	-	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0	-	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/231/0	-	-	3/231/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	3/231/0	3/231/0	-	3/231/0	-	-	-
HTOL	B1	Life Test	100C	300 Hours	1/77/0	-	-	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	-	-	3/231/0	3/231/0
HTOL	B1	Life Test	150C	408 Hours	-	-	-	-	3/231/0	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	-	3/228/0	-	-	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	3/228/0	3/228/0	-	-
SD	C3	PB Solderability	Post 8hr steam	-	-	-	-	-	3/45/0	-	-
SD	C3	PB-Free Solderability	Post 8hr steam	-	-	-	-	-	3/45/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	-	-	1/22/0	-
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	-	3/15/0	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	3/30/0	-	-
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	1/30/0	-	3/90/0	1/30/0	-	1/30/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	3/90/0	1/30/0	-	1/30/0	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	3/90/0	-	-

QBS: Qual By Similarity, also known as Generic Data
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2602-071

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification

by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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